

**[0091]** The substrate processing system 1 according to the above-described exemplary embodiment is configured to be capable of coping with any of two cases: where the laser processing of the processing target substrate 10 is performed before the thinning of the processing target substrate 10 and where the thinning of the processing target substrate 10 is performed before the laser processing. However, the substrate processing system 1 may be configured to be capable of coping with either one of these cases. By way of example, when the substrate processing system 1 is adapted to correspond to only the case where the thinning of the processing target substrate 10 is first performed, the substrate processing system 1 may not have the transfer arm 260.

**[0092]** The substrate processing system 1 according to the above-described exemplary embodiment is configured to perform both the laser processing of the processing target substrate 10 and the thinning of the processing target substrate 10. However, the substrate processing system 1 may be configured to perform only the laser processing of the processing target substrate 10 and may not have the thinning apparatus 270. In this case, upon the completion of the process S112 of **FIG. 10**, the processing target substrate 10 is accommodated in the cassette placed on the cassette table 110 after being transferred through the transfer section 120. Then, the current processing is ended.

**[0093]** The present application claims priority to Japanese Patent Application No. 2018-086913, filed on April 27, 2018, which application is hereby incorporated by reference in their entirety.